

In the Abstract:

ABSTRACT OF THE DISCLOSURE

~~Optoelectronic component and a module based thereon~~

~~The invention proposes an~~ An optoelectronic component (1) having a semiconductor arrangement (4) which emits and/or receives electromagnetic radiation and which is arranged on a carrier (22) which is thermally conductively connected to a heat sink (12). External ~~, and having external~~ electrical connections (9) ~~which~~ are connected to the semiconductor arrangement (4), where the external electrical connections (9) are arranged in electrically insulated fashion on the heat sink (12) at a distance from the carrier (22). This results in an optimized component in terms of the dissipation of heat loss and the radiation of light and also in terms of making electrical contact and the packing density in modules.

FIGURE